

INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Not for submission under 37 CFR 1.99)	Application Number		10733226
	Filing Date		2003-12-10
	First Named Inventor	William M. Hiaft	
	Art Unit	2811	
	Examiner Name	C. A. Matthews	
	Attorney Docket Number	108298744US	

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3	BLACKBURN, J.M. et al., "Deposition of Conformal Copper and Nickel Films from Supercritical Carbon Dioxide," Science, Vol. 94, October 2001, pp. 141-145.	<input type="checkbox"/>
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